IXYS

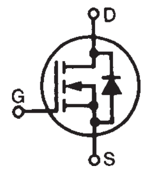
Advance Technical Information

Linear™ Power MOSFET w/Extended FBSOA

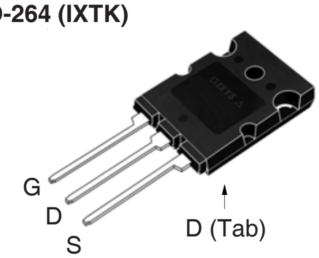
IXTK3N250L
IXTX3N250L

V_{DSS} = 2500V
I_{D25} = 3A
$R_{DS(on)}$ ≤ 8.3Ω

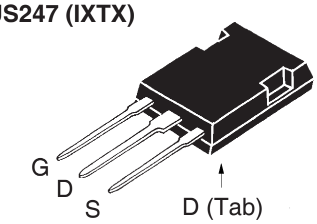
N-Channel Enhancement Mode



TO-264 (IXTK)



PLUS247 (IXTX)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	2500	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	2500	V
V_{GSS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	3	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	8	A
P_D	T_C = 25°C	417	W
T_J		-55...+150	°C
T_{JM}		150	°C
T_{stg}		-55...+150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
M_d	Mounting Torque (TO-264)	1.13/10	Nm/lb.in
F_C	Mounting Force (PLUS247)	20..120 /4.5..27	N/lb
Weight	TO-264	10	g
	PLUS247	6	g

Features

- Designed for linear operation
- International standard packages
- Guaranteed FBSOA at 75°C

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- Solid state circuit breakers
- Soft start controls
- Linear amplifiers
- Programmable loads
- Current regulators

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 1mA	2500			V
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 1mA	2.5		4.5	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±200	nA
I_{DSS}	V_{DS} = 0.8 • V_{DSS}, V_{GS} = 0V			50	µA
	T_J = 125°C			2	mA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 0.5 • I_{D25}, Note 1			8.3	Ω

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Min.	Typ.	Max.	
g_{fs}	V_{DS} = 30V, I_D = 1.5A, Note 1	0.6	1.0	1.4	S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		5400		pF
C_{oss}			260		pF
C_{rss}			63		pF
$t_{d(on)}$	**Resistive Switching Times** V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25} R_G = 1Ω (External)		44		ns
t_r			32		ns
$t_{d(off)}$			120		ns
t_f			160		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		230		nC
Q_{gs}			58		nC
Q_{gd}			100		nC
R_{thJC}				0.30	°C/W
R_{thCS}			0.15		°C/W

Safe Operating Area Specification

Symbol	Test Conditions	Min.	Typ.	Max.	
SOA	V_{DS} = 2kV, I_D = 125mA, T_C = 75°C, Tp = 5s	250			W

Source-Drain Diode

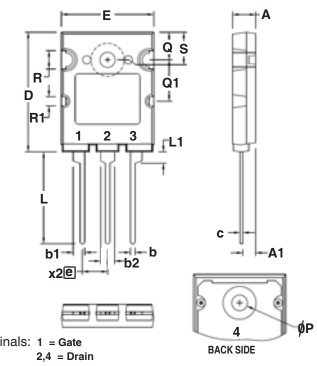
Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Min.	Typ.	Max.	
I_S	V_{GS} = 0V			3	A
I_{SM}	Repetitive, pulse width limited by T_{JM}			12	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 1.5A, -di/dt = 100A/μs, V_R = 100V, V_{GS} = 0V		370		ns
I_{RM}			18.4		A
Q_{RM}			3.4		μC

Note: 1. Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

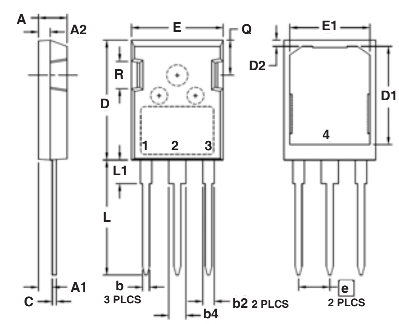
TO-264 Outline



Terminals: 1 = Gate
2,4 = Drain
3 = Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.70	5.30
A1	.102	.118	2.60	3.00
b	.035	.049	0.90	1.25
b1	.091	.106	2.30	2.70
b2	.110	.126	2.80	3.20
c	.020	.033	0.50	0.85
D	1.012	1.035	25.70	26.30
E	.776	.799	19.70	20.30
e	.215BSC		5.46 BSC	
L	.768	.807	19.50	20.50
L1	.091	.106	2.30	2.70
ØP	.122	.138	3.10	3.50
Q	.228	.244	5.80	6.20
Q1	.346	.362	8.80	9.20
ØR	.150	.165	3.80	4.20
ØR1	.071	.087	1.80	2.20
S	.228	.244	5.80	6.20

PLUS 247™ Outline



Terminals: 1 - Gate
2,4 - Drain
3 - Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.520	.560	13.08	14.22
e	.215 BSC		5.45 BSC	
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83

Fig. 1. Output Characteristics @ $T_J = 25^oC$

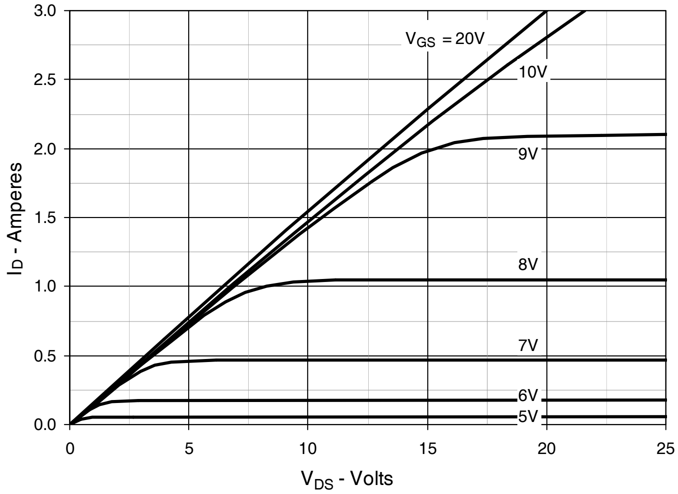


Fig. 2. Extended Output Characteristics @ $T_J = 25^oC$

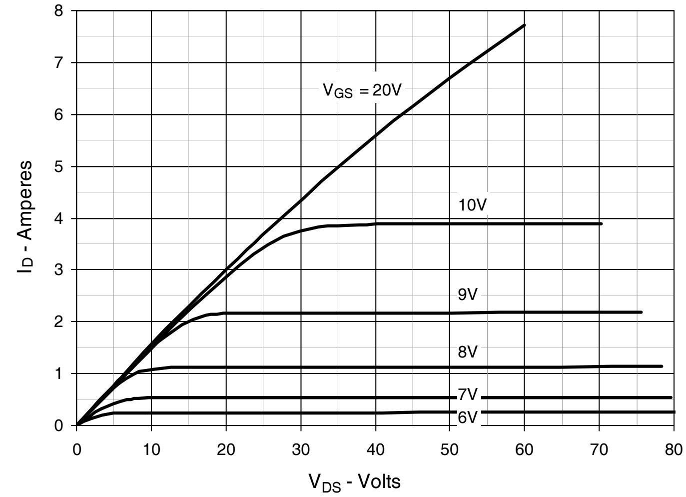


Fig. 3. Output Characteristics @ $T_J = 125^oC$

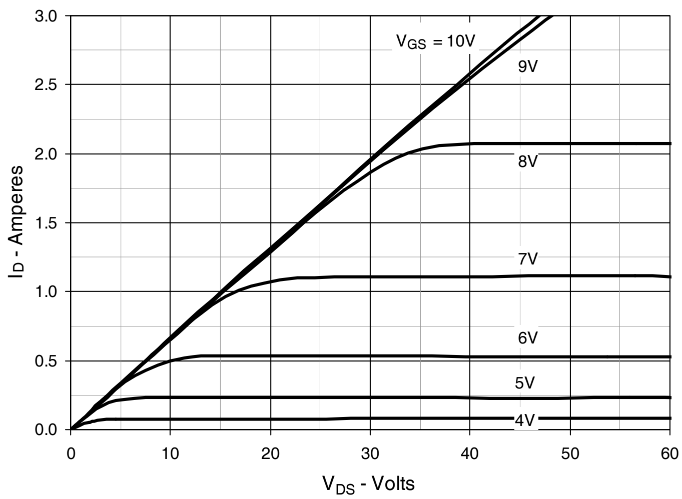


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 1.5A Value vs. Junction Temperature

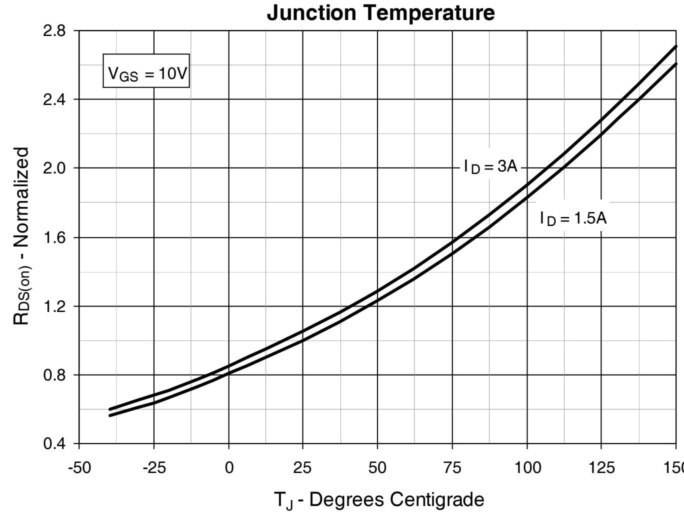


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 1.5A Value vs. Drain Current

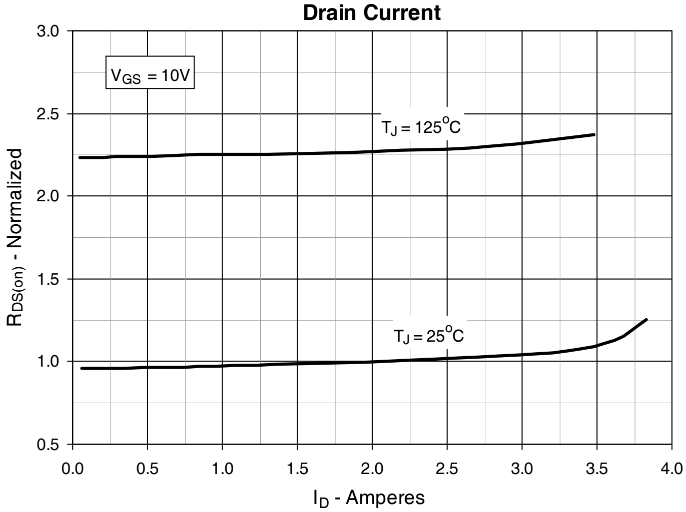


Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

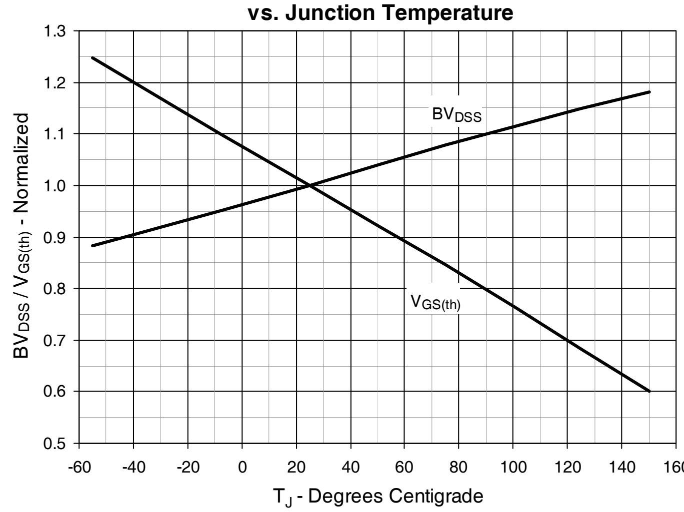


Fig. 7. Maximum Drain Current vs. Case Temperature

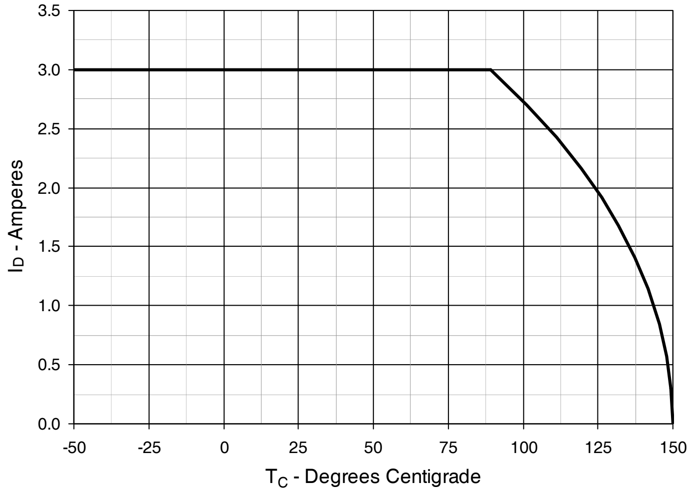


Fig. 8. Input Admittance

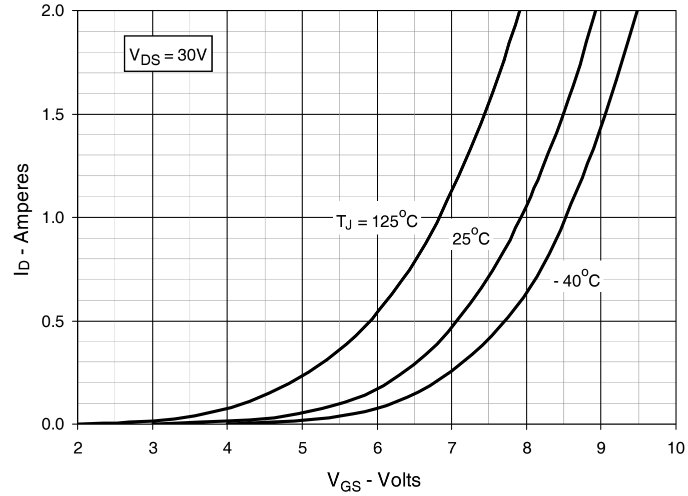


Fig. 9. Transconductance

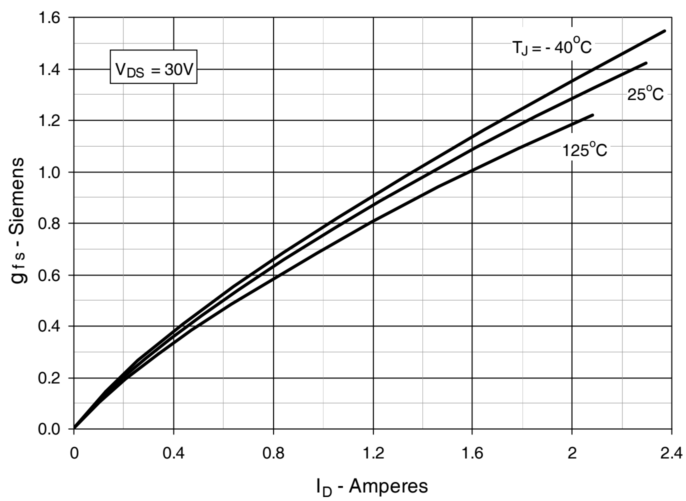


Fig. 10. Forward Voltage Drop of Intrinsic Diode

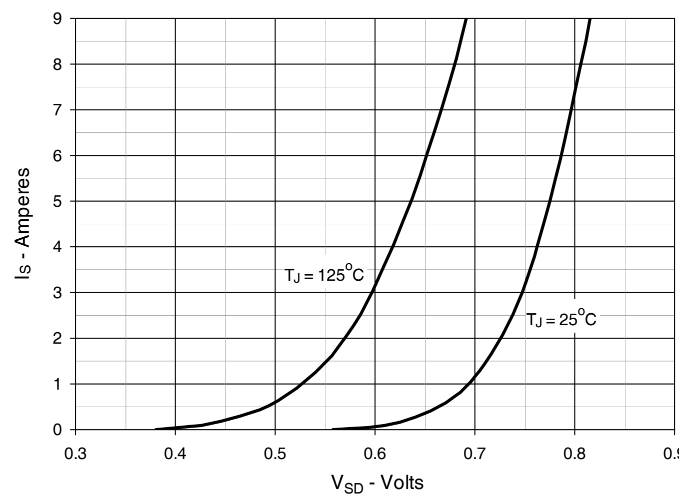


Fig. 11. Gate Charge

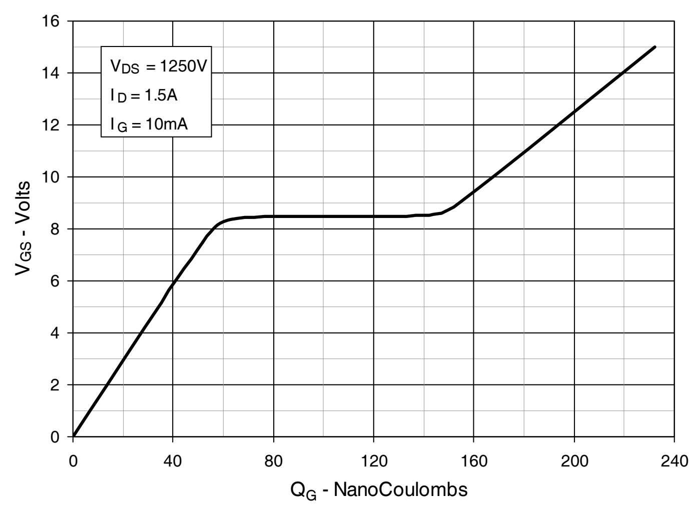


Fig. 12. Capacitance